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(12) **United States Design Patent**
Ignomirello

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(54) **TRAY**

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(73) Assignee: **SYMBOLIC IO CORPORATION**, Holmdel, NJ (US)

(**) Term: **15 Years**

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(51) **LOC (10) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/439**; D14/432

(58) **Field of Classification Search**
USPC D14/300–302, 308–313, 314, 348, D14/353–355, 432, 439–446, 240; 361/679.02, 679.31, 679.5, 690, 694, 361/679.23, 801, 802; 312/332.1, 334.1; D13/162; D10/50
CPC B65H 1/00; B65H 1/266; B65H 2402/441; B65H 2405/311; B65H 2405/313
See application file for complete search history.

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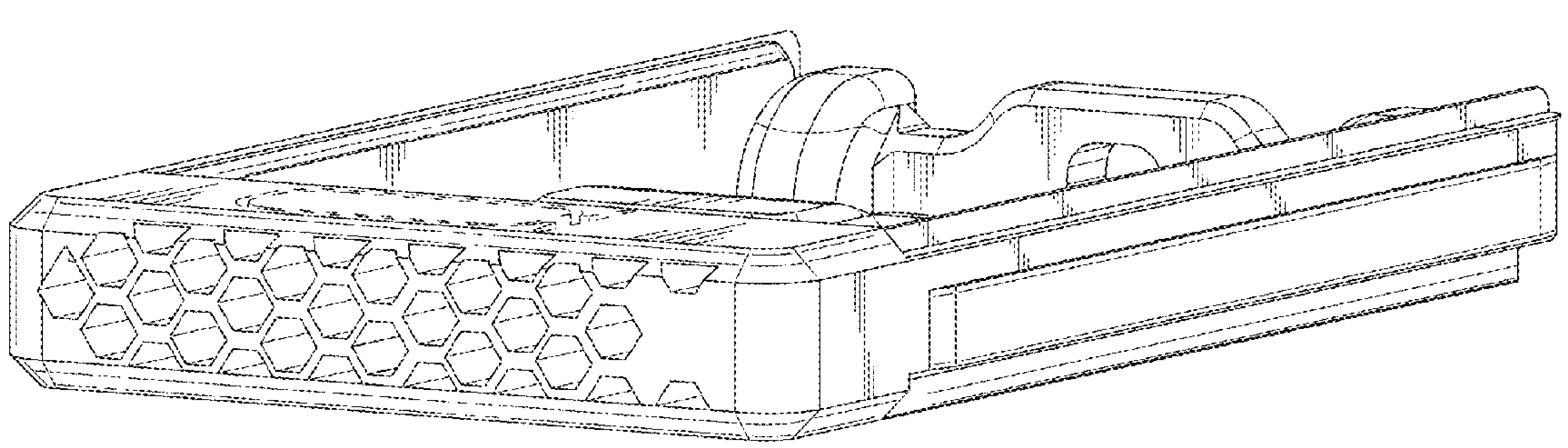
(57) **CLAIM**

The ornamental design for a tray, as shown and described.

DESCRIPTION

FIG. **1** is a top and right side perspective view of a tray showing my new design;
FIG. **2** is a front plan view thereof;
FIG. **3** is a rear plan view thereof;
FIG. **4** is a bottom and right side perspective view thereof;
FIG. **5** is a top and left side perspective view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof;
FIG. **8** is a right side plan view thereof; and,
FIG. **9** is a left side plan view thereof.

1 Claim, 9 Drawing Sheets



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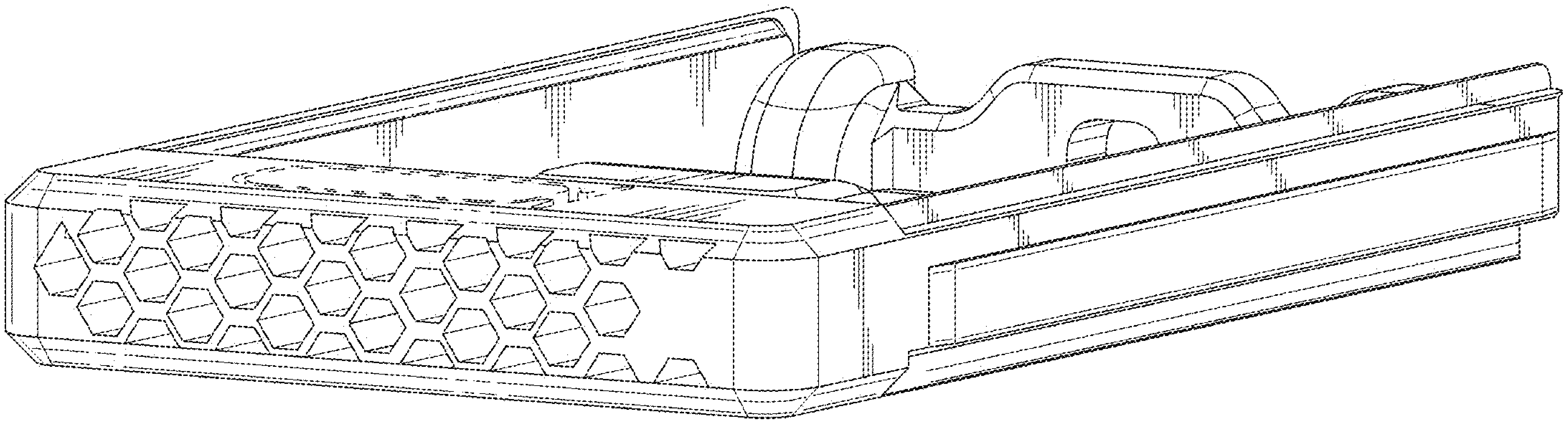

FIG. 1

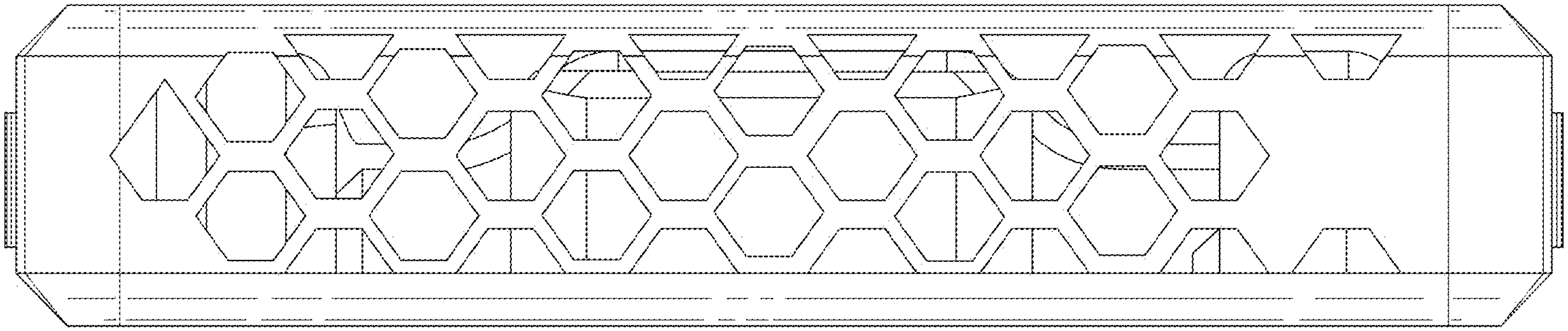

FIG. 2

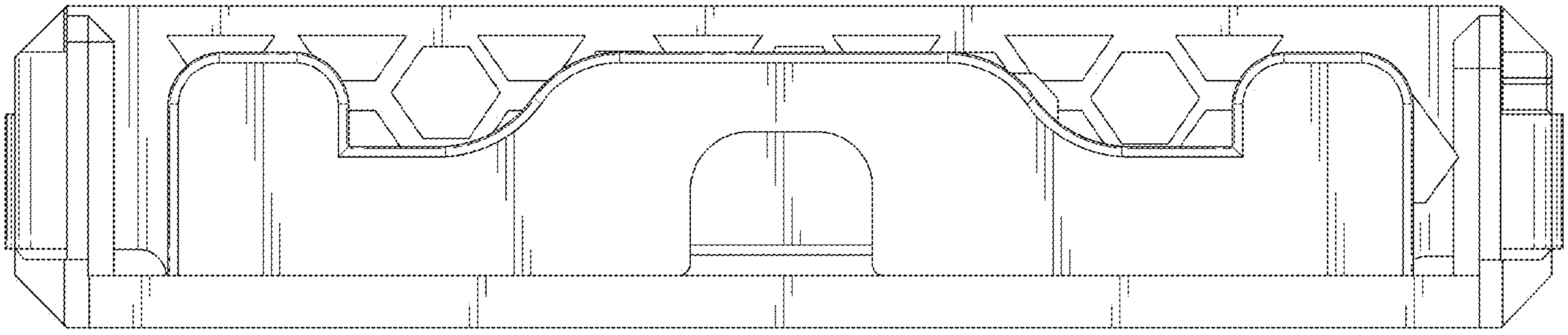

FIG. 3

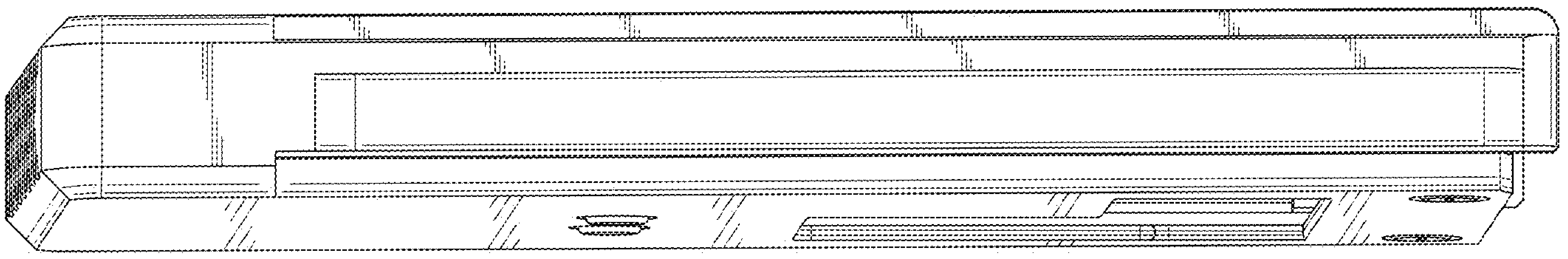

FIG. 4

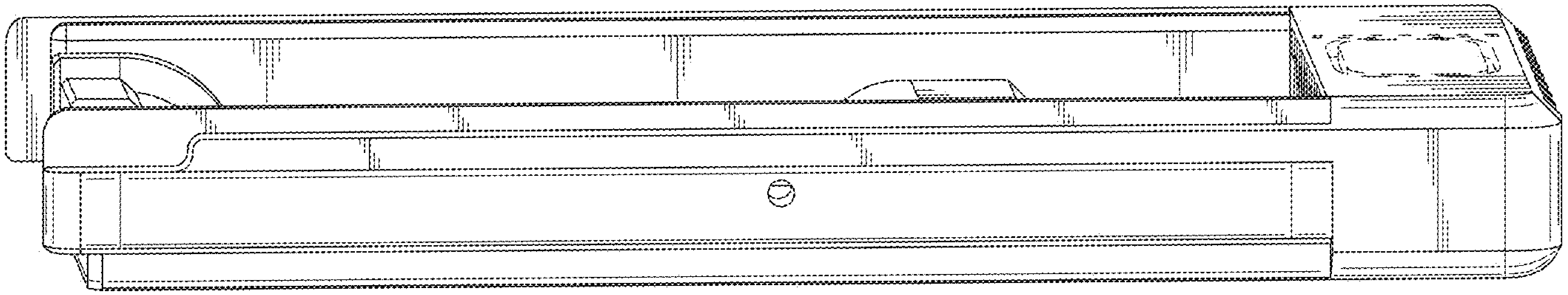

FIG. 5

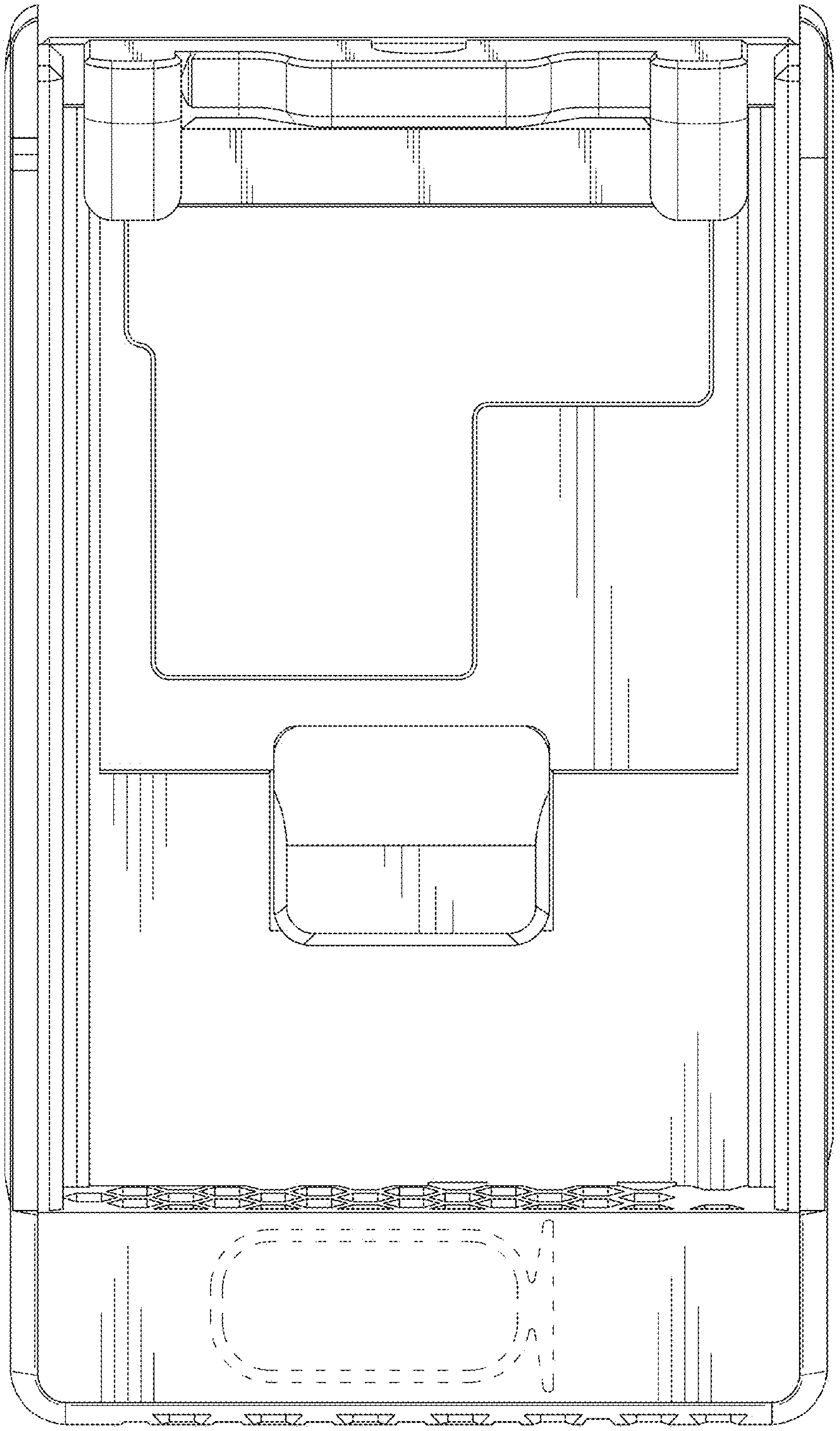

FIG. 6

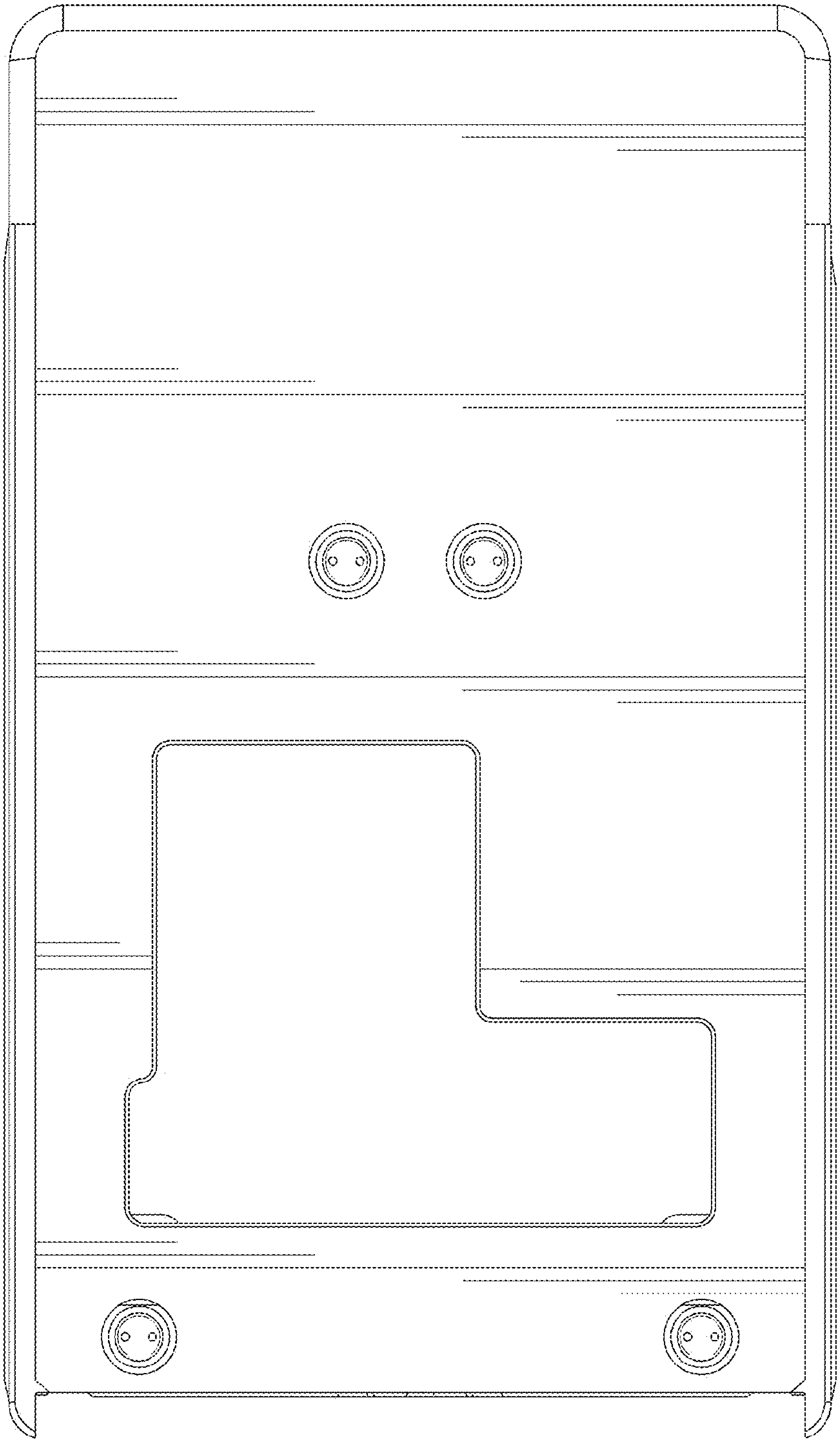

FIG. 7

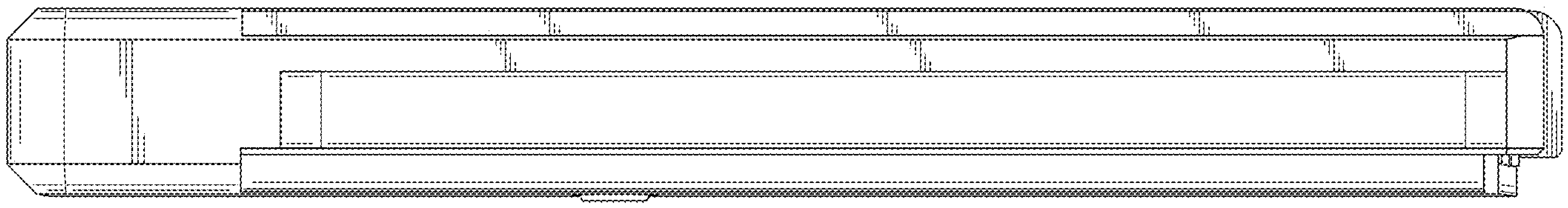

FIG. 8

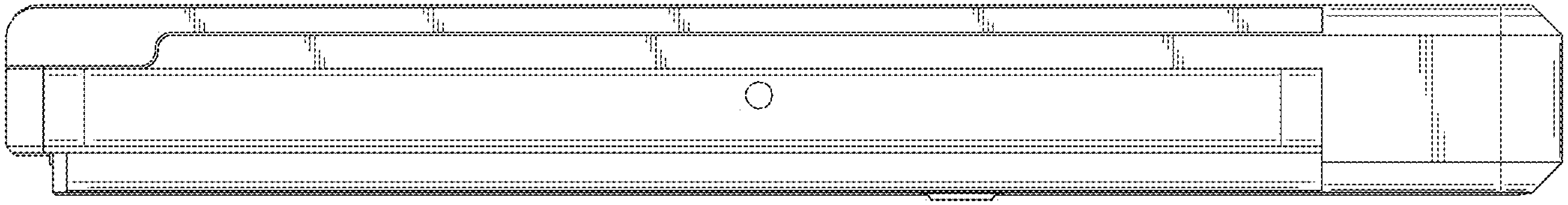

FIG. 9